

# PMEG060T100CLPE

60 V, 2 x 5 A dual common cathode low leakage current Trench MEGA Schottky barrier rectifier Product data sheet

27 April 2020

# 1. General description

Trench Maximum Efficiency General Application (MEGA) dual Schottky barrier rectifier in common cathode configuration encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

### 2. Features and benefits

- Reverse voltage: V<sub>R</sub> ≤ 60 V
- Forward current: I<sub>F</sub> ≤ 5 A (per diode)
- Low forward voltage
- Low leakage current due to Trench MEGA Schottky technology
- Power and flat lead SMD plastic package
- Package height typical 0.95 mm
- High power capability due to clip-bond technology
- AEC-Q101 qualified

# 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications
- Freewheeling applications

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
Per diode (unl	Per diode (unless otherwise specified)							
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; square wave; f = 20 kHz; T <sub>sp</sub> $\leq$ 155 °C		-	-	5	Α	
V <sub>R</sub>	reverse voltage	T <sub>j</sub> = 25 °C		-	-	60	V	
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 5 A; T <sub>j</sub> = 25 °C	[1]	-	610	690	mV	
I <sub>R</sub>	reverse current	V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C	[1]	-	0.14	0.9	μA	
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 25 °C	[1]	-	0.3	1.8	μΑ	

[1] Very short pulse, in order to maintain a stable junction temperature.



# 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode (diode 1)	5	[CC]
2	A2	anode (diode 2)		
3	CC	common cathode	CFP15B (SOT1289B)	A1 A2 006aab034

# 6. Ordering information

#### **Table 3. Ordering information**

Type number	Package						
	Name	Description	Version				
PMEG060T100CLPE	CFP15B	plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; $5.8 \times 4.3 \times 0.95$ mm body	SOT1289B				

## 7. Marking

#### Table 4. Marking codes

Type number	Marking code
PMEG060T100CLPE	060T L10C

# 8. Limiting values

### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per diode (unle	ss otherwise specified)			'		•
V <sub>R</sub>	reverse voltage	T <sub>j</sub> = 25 °C		-	60	V
l <sub>F</sub>	forward current	δ = 1; T <sub>sp</sub> ≤ 154 °C		-	7.1	Α
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; square wave; f = 20 kHz; T <sub>sp</sub> ≤ 155 °C		-	5	A
	non-repetitive peak forward current	t <sub>p</sub> = 8.3 ms; half sine wave; T <sub>j(init)</sub> = 25 °C		-	80	Α
		$t_p$ = 8.3 ms; half sine wave; per device; $T_{j(init)}$ = 25 °C		-	150	A
Per device, one	diode loaded			'		,
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	1.66	W
			[2]	-	2.15	W
T <sub>j</sub>	junction temperature			-	175	°C
T <sub>amb</sub>	ambient temperature			-55	175	°C
T <sub>stg</sub>	storage temperature			-65	175	°C

Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
	e diode loaded	- Contains no			- 7 P	1110.21	J
rei device, oii	e diode ioaded						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	90	K/W
			[1] [3]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	7	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Soldering point of cathode tab.

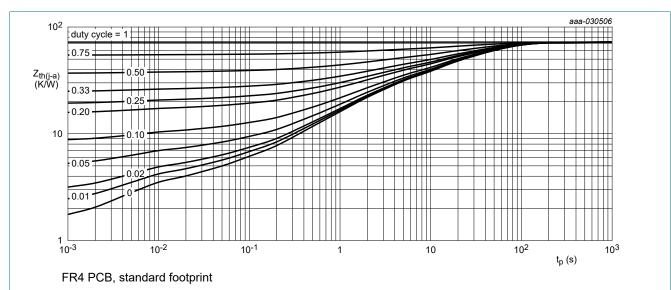


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

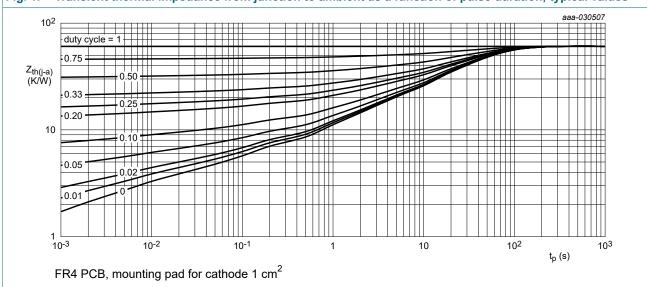


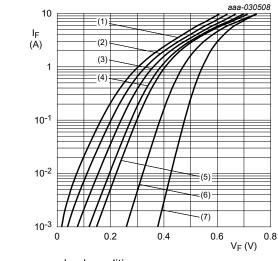
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

### 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Per diode (ı	unless otherwise specified	1)					
$V_{(BR)R}$	reverse breakdown voltage	I <sub>R</sub> = 1 mA; T <sub>j</sub> = 25 °C	[1]	60	-	-	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.5 A; T <sub>j</sub> = 25 °C	[1]	-	440	510	mV
		I <sub>F</sub> = 1 A; T <sub>j</sub> = 25 °C	[1]	-	470	540	mV
		I <sub>F</sub> = 5 A; T <sub>j</sub> = 25 °C	[1]	-	610	690	mV
		I <sub>F</sub> = 5 A; T <sub>j</sub> = -40 °C	[1]	-	650	740	mV
		I <sub>F</sub> = 5 A; T <sub>j</sub> = 125 °C	[1]	-	550	650	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C	[1]	-	0.14	0.9	μΑ
		V <sub>R</sub> = 40 V; T <sub>j</sub> = 25 °C	[1]	-	0.18	1.2	μΑ
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 25 °C	[1]	-	0.3	1.8	μΑ
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 125 °C	[1]	-	0.5	3	mA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	560	-	рF
		$V_R = 10 \text{ V; } f = 1 \text{ MHz; } T_j = 25 \text{ °C}$		-	180	-	pF
t <sub>rr</sub>	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$ $T_j = 25 ^{\circ}\text{C}$		-	17	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 200 \text{ A/}\mu\text{s}; I_F = 6 \text{ A}; V_R = 26 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$		-	11	-	ns
$V_{FRM}$	peak forward recovery voltage	$I_F = 0.5 \text{ A}; \text{ d}I_F/\text{d}t = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	460	-	mV

<sup>[1]</sup> Very short pulse, in order to maintain a stable junction temperature.



pulsed condition

(1)  $T_i = 175 \,^{\circ}C$ 

(2)  $T_i = 150 °C$ 

(3)  $T_i = 125 °C$ 

 $(4) T_i = 100 °C$ 

(5)  $T_i = 85$  °C

(6)  $T_i = 25 \,^{\circ}\text{C}$ 

 $(7) T_i = -40 ^{\circ}C$ 

Fig. 3. Forward current as a function of forward voltage; typical values

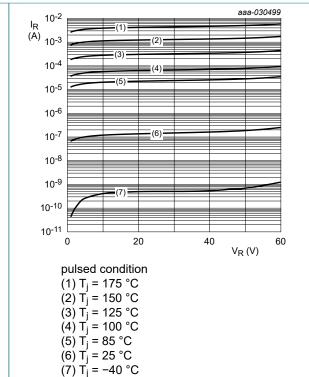
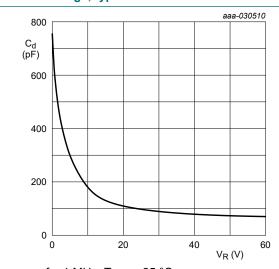
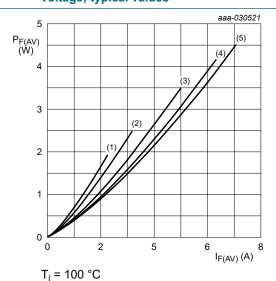


Fig. 4. Reverse current as a function of reverse voltage; typical values



f = 1 MHz; T<sub>amb</sub> = 25 °C

Diode capacitance as a function of reverse voltage; typical values

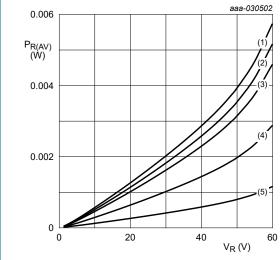


 $(1) \delta = 0.1$   $(2) \delta = 0.2$   $(3) \delta = 0.5$  $(4) \delta = 0.8$ 

(5)  $\delta = 1$ ; DC

Fig. 6. Average forward power dissipation as a function of average forward current; typical values

Fig. 5.



 $T_j = 100 \,^{\circ}C$ 

 $(1) \delta = 1; DC$ 

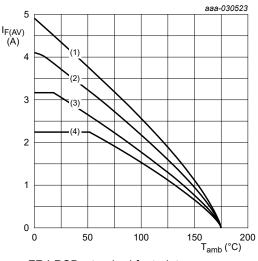
 $(2) \delta = 0.9$ 

 $(3) \delta = 0.8$ 

 $(4) \delta = 0.5$ 

 $(5) \delta = 0.2$ 

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T<sub>i</sub> = 175 °C

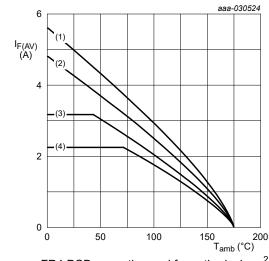
 $(1) \delta = 1$ ; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

 $T_j = 175 \,^{\circ}C$ 

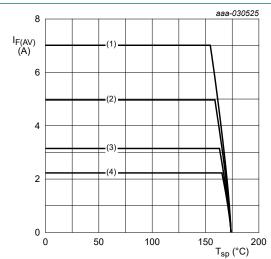
 $(1) \delta = 1; DC$ 

 $(2) \delta = 0.5$ ; f = 20 kHz

(3)  $\delta$  = 0.2; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



T<sub>i</sub> = 175 °C

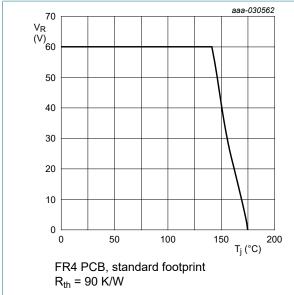
 $(1) \delta = 1; DC$ 

(2)  $\delta$  = 0.5; f = 20 kHz

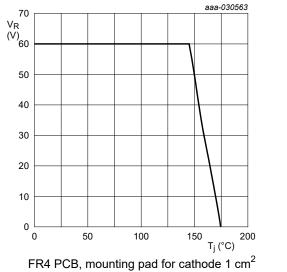
(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

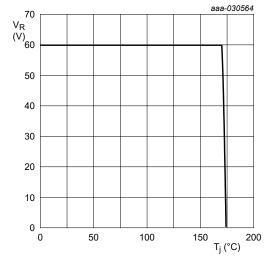


of junction temperature; typical values



 $R_{th} = 70 \text{ K/W}$ 

Fig. 11. Derated maximum reverse voltage as a function | Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



Soldering point of cathode tab  $R_{th} = 7 \text{ K/W}$ 

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

# 11. Test information

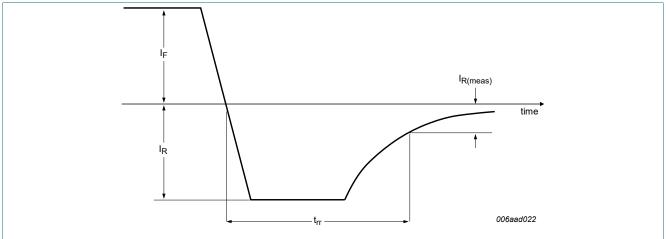


Fig. 14. Reverse recovery definition; step recovery

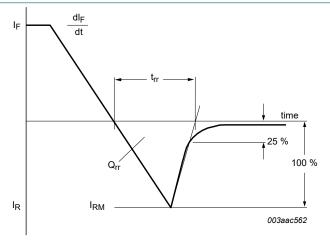


Fig. 15. Reverse recovery definition; ramp recovery

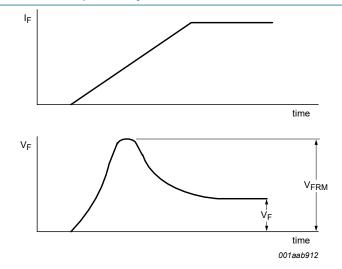
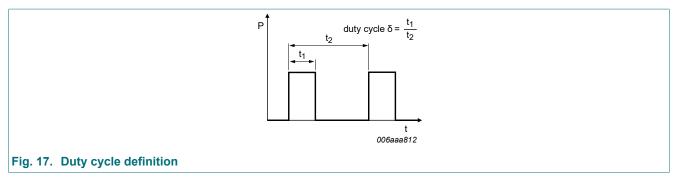


Fig. 16. Forward recovery definition



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current

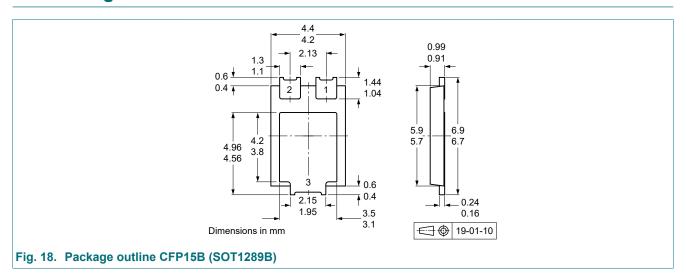
 $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_{M} \times \sqrt{\delta}$ 

with  $I_{\mbox{\scriptsize RMS}}$  defined as RMS current.

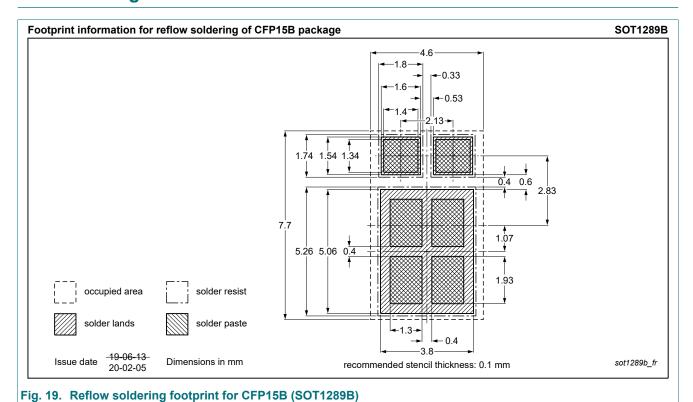
### **Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

# 12. Package outline



# 13. Soldering



# 14. Revision history

### **Table 8. Revision history**

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes				
PMEG060T100CLPE v.2	20200427	Product data sheet	-	PMEG060T100CLPE v.1				
Modifications:	Product status of	changed						
PMEG060T100CLPE v.1	20200304	Objective data sheet	-	-				

# 15. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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